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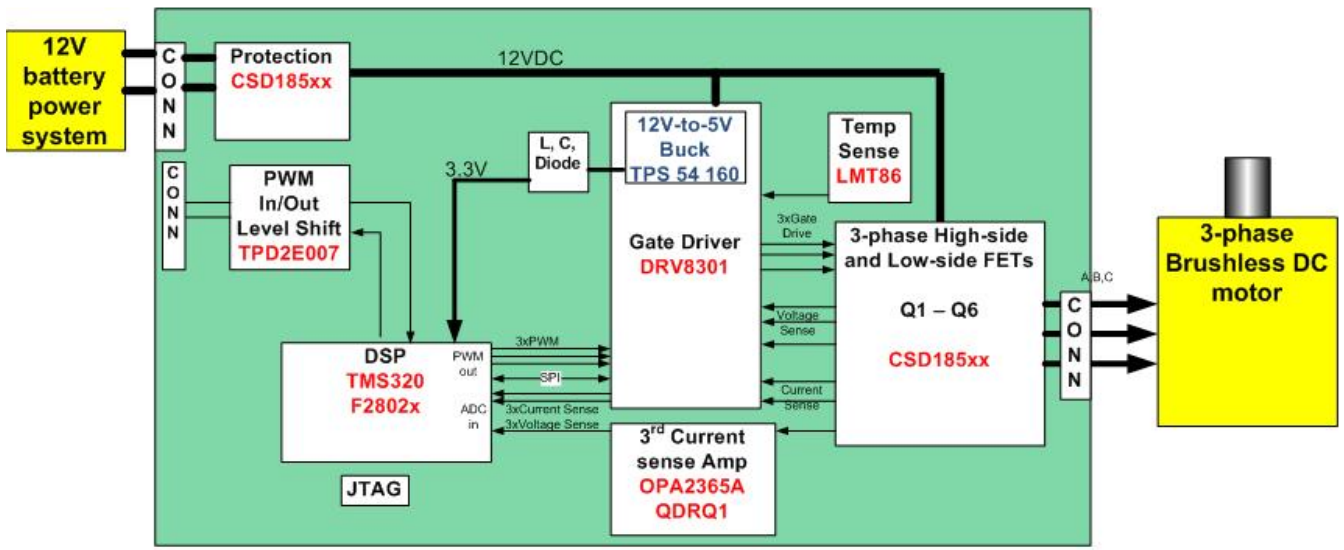
Revision History	
Revision	Notes



Designed for: Public Release		Mod. Date: 2/6/2014	
Project Title: Automotive BLDC Motor Drive			
Number: SAT0042	Rev: E5	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 0 of 4
Drawn By:		File: BLDC Standard sheet cover.SchDoc	Size: B
Engineer: Clark Kinnaird		Contact: http://www.ti.com/support	

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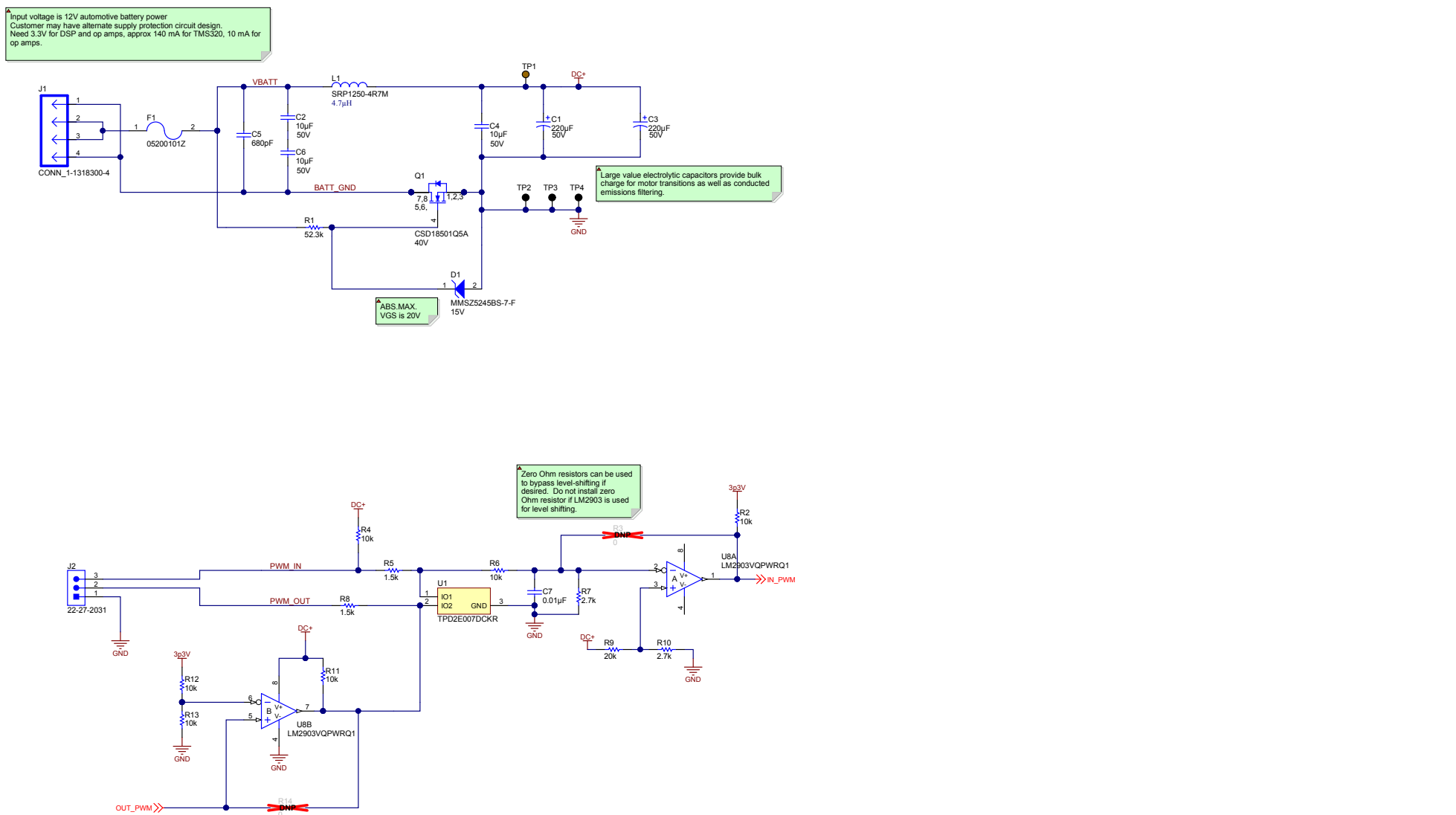

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Project Title: Automotive BLDC Motor Drive			
Number: SAT0042	Rev: E5	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 1 of 4
Drawn By:		File: BLDC Standard sheet 1.SchDoc	Size: B
Engineer: Clark Kinnaird		Contact: http://www.ti.com/support	

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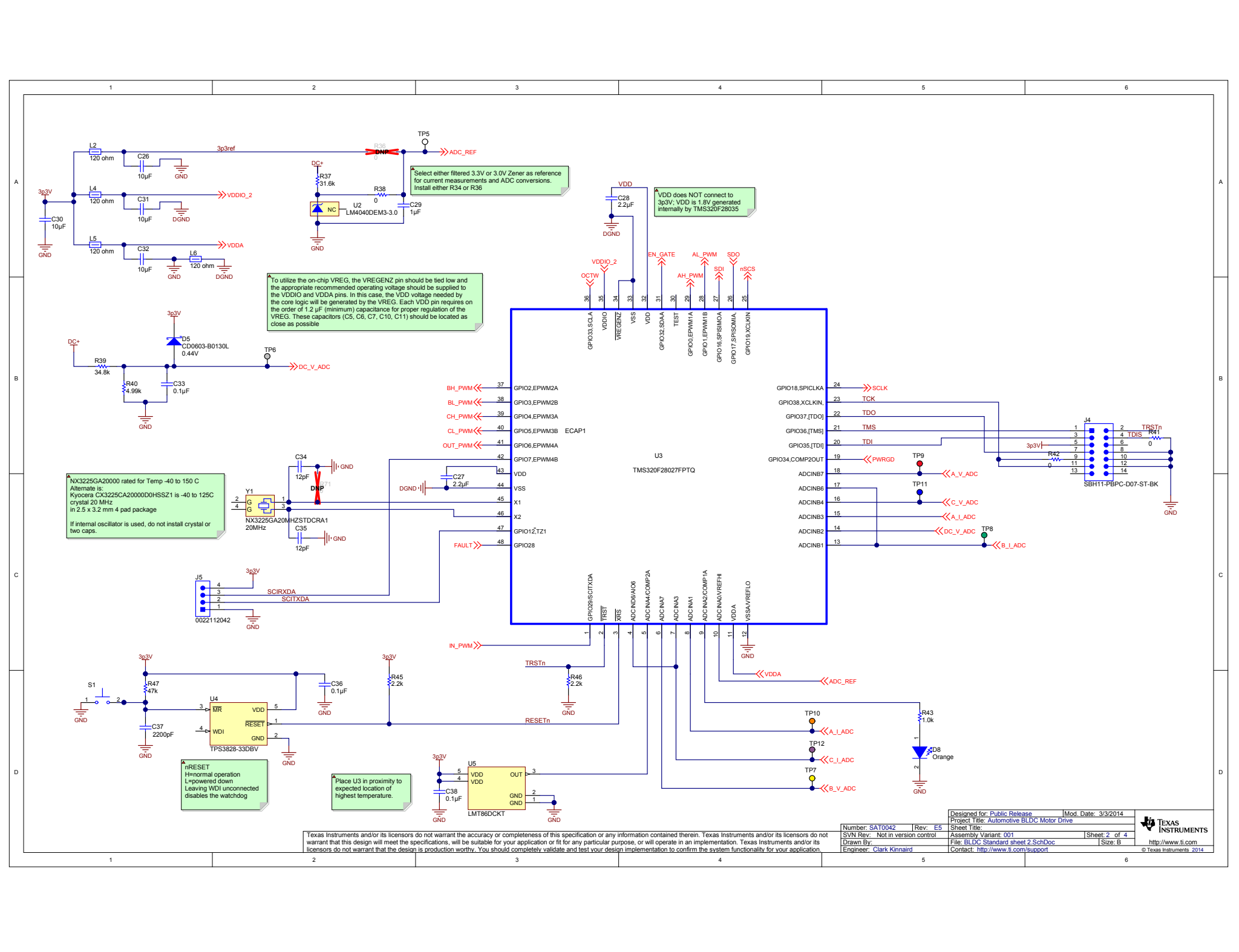

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Project Title: Automotive BLDC Motor Drive			
Number: SAT0042	Rev: E5	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 2 of 4
Drawn By:		File: BLDC Standard sheet 2.SchDoc	Size: B
Engineer: Clark Kinnaird		Contact: http://www.ti.com/support	

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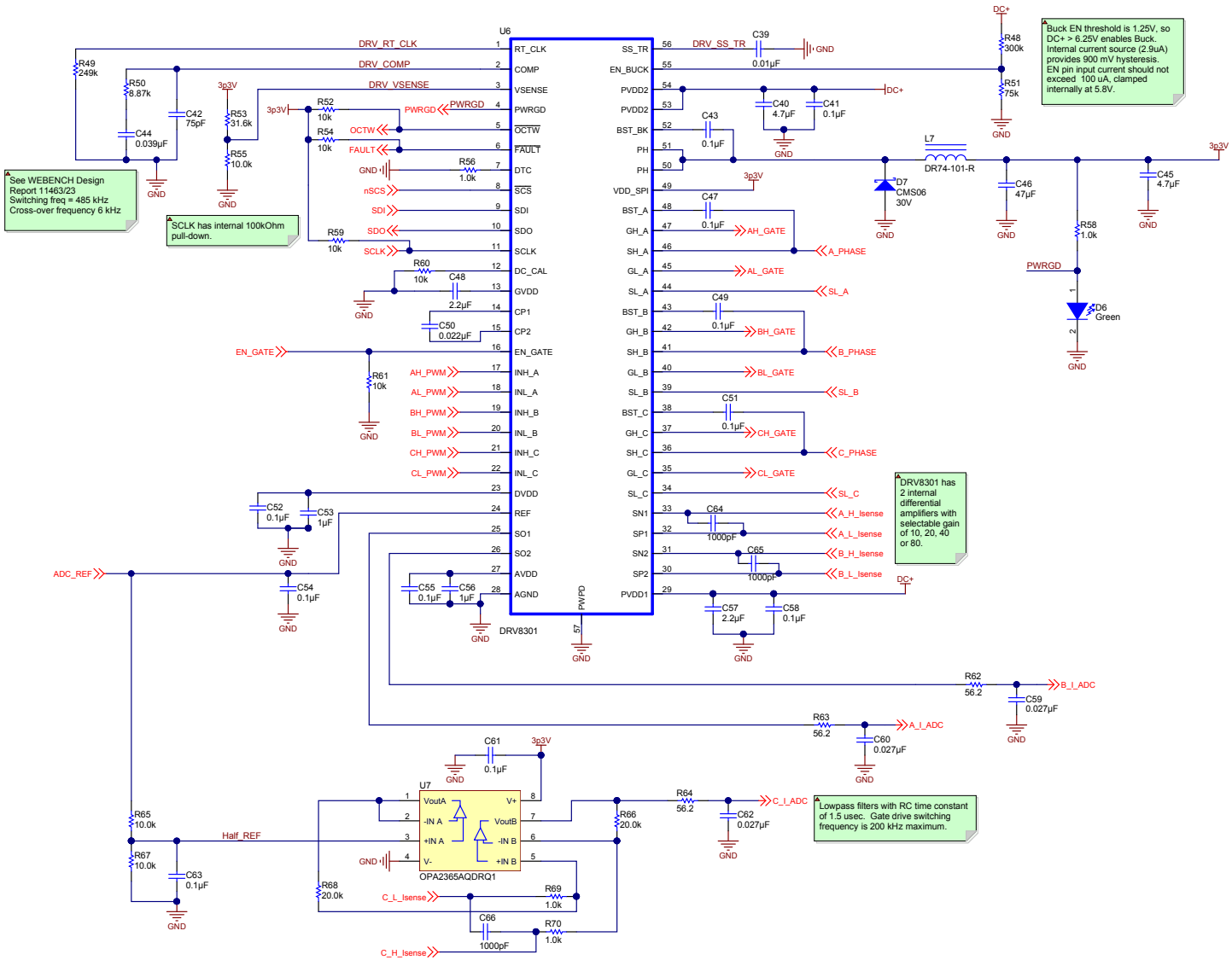

Designed for: Public Release	Mod. Date: 2/6/2014		
Project Title: Automotive BLDC Motor Drive			
Number: SAT0042	Rev: E5	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 3 of 4
Drawn By:		File: BLDC Standard sheet 3.SchDoc	Size: B
Engineer: Clark Kinnaird		Contact: http://www.ti.com/support	

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FID1

H3
NY PMS 440 0025 PH

H1
1902C

H4
NY PMS 440 0025 PH

H2
1902C

PCB Number: SAT0042
PCB Rev: E5

PCB
LOGO
Texas Instruments

H7
NY PMS 440 0025 PH

H5
1902C

H8
NY PMS 440 0025 PH

H6
1902C

FID2

FID3

LBL1

PCB Label

Size: 0.65" x 0.20 "

ZZ1

Label Assembly Note

This Assembly Note is for PCB labels only

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

Designed for: Public Release		Mod. Date: 2/6/2014	
Project Title: Automotive BLDC Motor Drive			
Number: SAT0042	Rev: E5	Sheet Title: Hardware	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 4 of 4
Drawn By:		File: Hardware_ANSI-B.SchDoc	Size: B
Engineer: Clark Kinnaird		Contact: http://www.ti.com/support	

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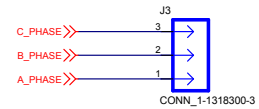
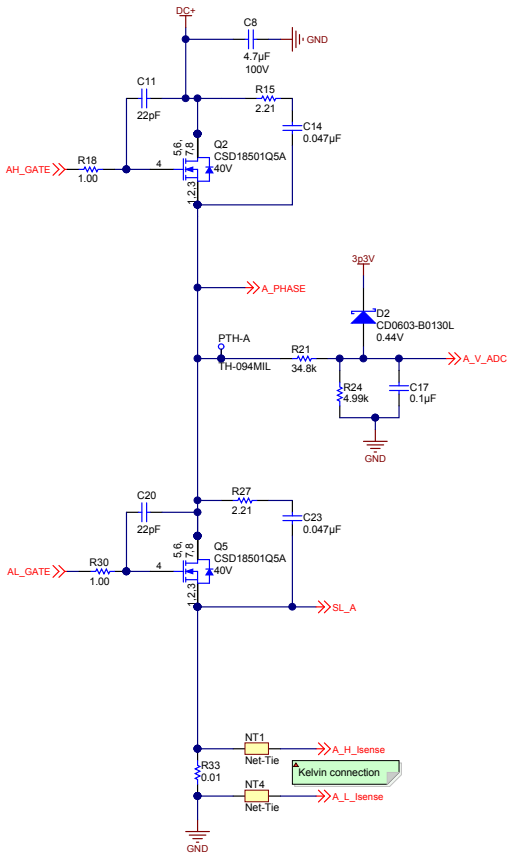
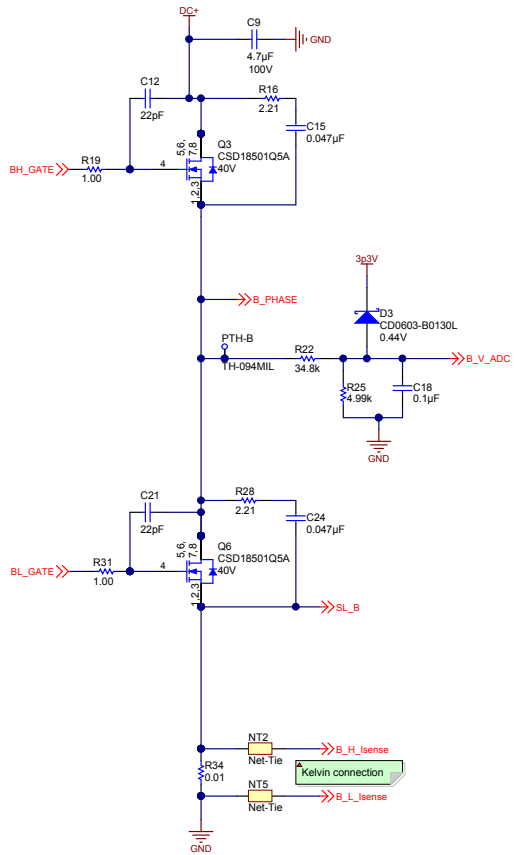
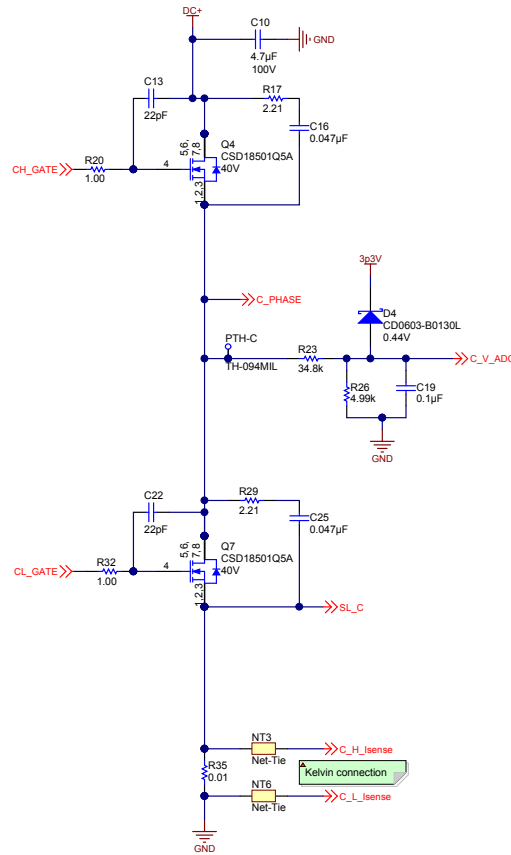
Keep trace distance between Source pins of High-side FET and Drain pins of Low-side FET as short as possible.









Number: SAT0042	Rev: E5	Designed for: Public Release	Mod. Date: 2/6/2014
		Project Title: Automotive BLDC Motor Drive	
		Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 4 of 4
Drawn By:		File: BLDC Standard sheet 4.SchDoc	Size: B
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